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Bib Data Sheet

CONFIRMATION NO. 1120

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|------------------------------------|--|---------------------|---------------------------------------|--|
| SERIAL NUMBER 09/687,048 | FILING DATE 10/13/2000 RULE 1.47 | CLASS 257 | GROUP ART UNIT 2811 2814 | ATTORNEY DOCKET NO. 45475-00026 99-44650 |
|------------------------------------|--|---------------------|---------------------------------------|--|

APPLICANTS

Tae Heon Lee, Kuri-shi, KOREA, REPUBLIC OF;
Young Suk Chung, Seoul, KOREA, REPUBLIC OF;
Mu Hwan Seo, Singapore, SINGAPORE;

** CONTINUING DATA *****

** FOREIGN APPLICATIONS *****

REPUBLIC OF KOREA 99-44650 10/15/1999

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

** 11/22/2000

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|--|---|----------------------------|---------------------------|--------------------------------|
| Foreign Priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no | STATE OR COUNTRY KOREA, REPUBLIC OF | SHEETS DRAWING 7 | TOTAL CLAIMS 15 | INDEPENDENT CLAIMS 4 |
| 35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance | | | | |
| Verified and Acknowledged | Examiner's Signature | Initials | | |

ADDRESS

Stanley R. Moore, Esq.
Jenkins and Gilchrist, P.C.
3200 Fountain Place
1445 Ross Ave.
Dallas, TX 75202

TITLE

Leadframe and semiconductor package with improved solder joint strength

| | | |
|-----------------------------------|---|--|
| FILING FEE RECEIVED 920 | FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following: | <input type="checkbox"/> All Fees |
| | | <input type="checkbox"/> 1.16 Fees (Filing) |
| | | <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) |
| | | <input type="checkbox"/> 1.18 Fees (Issue) |
| | | <input type="checkbox"/> Other _____ |
| | | <input type="checkbox"/> Credit |



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| APPLICANTS Tae Heon Lee, Kuri-shi, KOREA, REPUBLIC OF; Young Suk Chung, Seoul, KOREA, REPUBLIC OF; Mu Hwan Seo, Singapore, SINGAPORE; | | | | | |
| ** CONTINUING DATA ***** | | | | | |
| ** FOREIGN APPLICATIONS ***** REPUBLIC OF KOREA 99-44650 10/15/1999 | | | | | |
| IF REQUIRED, FOREIGN FILING LICENSE GRANTED ** 11/22/2000 | | | | | |
| Foreign Priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no 35 USC 119 (a-d) conditions <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after met Allowance Verified and Acknowledged _____ Examiner's Signature Initials | | STATE OR COUNTRY KOREA, REPUBLIC OF | SHEETS DRAWING 7 | TOTAL CLAIMS 15 | INDEPENDENT CLAIMS 4 |
| ADDRESS 007663 | | | | | |
| TITLE Leadframe and semiconductor package with improved solder joint strength | | | | | |
| FILING FEE RECEIVED 920 | FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following: | | <input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees (Filing) <input type="checkbox"/> 1.17 Fees (Processing Ext. of time) <input type="checkbox"/> 1.18 Fees (Issue) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit | | |